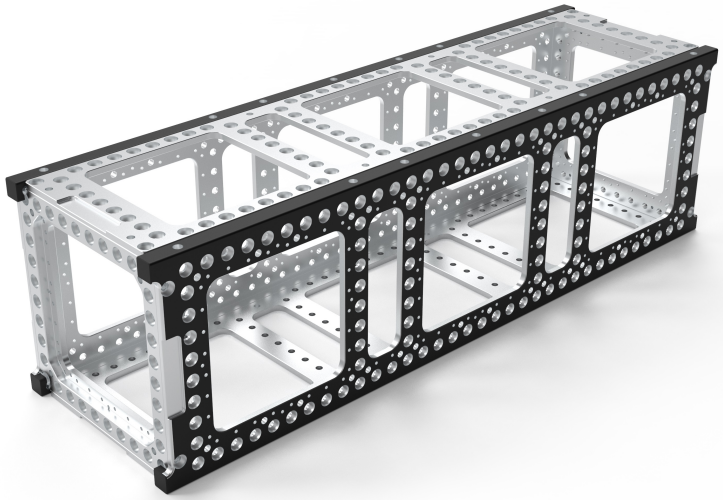
3U/ 3U PLUS STRUCTURE

DESCRIPTION

C3S's CubeSat structures are developed to provide optimal configurability. The design is based on simple modular elements and standard attachment points. Multiple subunit architectures can be accommodated, such as: stacked PCB-, backplane-, PCB card retainer- and cable harness design. The platform includes internal separation subframes in different sizes, full off possible interfaces, if the internal volume partition, or additional interface points are needed. With these features our platform represents a fully market ready and flexible solution in terms of innovative new space approach.

MAIN FEATURES

- High reliability electronic, structural, and thermal connections
- Access to individual cards and units during integration and testing
- Made of aluminium with ECSS standard elox coating along the rails
- Simplified stack-up tolerances
- Dedicated and independent thermal interfaces for all cards
- Optimized for high dissipation density



SPECIFICATION

Physical Properties

Primary Structure Mass	580g / 614g
Secondary Structure	Depending on payload
Outside envelope (mm)	100 x 100 x 340.5/ 100 x 100 x 366 *

* Depending on dispenser

Customization

PCB stack orientation	Longitudinal (Z), Lateral (X, Y)
PCB accomodation	PC 104 USF- pattern Custom design
TRL	TRL 3 (Finite Element and Thermal Analysis) TRL 6 (after planned Testing Campaign)